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Application ID:

10706468

Title of Invention:

SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS

AND METHOD OF

MANUFACTURING THE SAME

First Named Inventor:

Sung Yang

Domestic/Foreign Application:

Domestic Application

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Attorney Docket Number:

AMKOR095A

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Title of Invention SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD OF MANUFACTURING THE SAME

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First Named Applicant:

Sung Jin Yang

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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

Documents being submitted

Files

us-ids

ids6-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

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Application Number:

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First Named Applicant: Sung Yang Attorney Docket Number: AMKOR095A

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(6388336 or 6395578 or 6400004 or 6410979 or 6414385 or 6420779 or 6429508 or 6437429 or 6444499 or 6448633 or 6452279 or 6464121 or 6476474 or 6476469 or 6482680 or 6498392 or 6498099 or 6507120 or 6507096 or 6534849

or 6545345 or 6559525 or 6566168).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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	5	6414385	2002-07-02	HUANG ET AL.			
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Signature

Examiner Name	Date	